	REVISIONS		
LTR	DESCRIPTION	DATE (YR-MO-DA)	APPROVED
Α	Redrawn with changes. Added device types 05, 06, and 07 for cage code 32116. Made changes to table I and figures 1, 2, and 3.	94-04-08	K. A. Cottongim
В	Delete CAGE code 32116. Made changes to table I.	95-06-02	K. A. Cottongim
С	Inactivate device types 01, 05, and 07 for new design. Add device type 08.	98-06-05	K. A. Cottongim

THE ORIGINAL FIRST PAGE OF THIS DRAWING HAS BEEN REPLACED.

REV																				
SHEET																				
REV	С	С	С	С	С	С	С													
SHEET	15	16	17	18	19	20	21													
REV STATUS	3			RE'	٧		С	С	С	С	С	С	С	С	С	С	С	С	С	С
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PMIC N/A				PREPARED BY Donald R. Osborne						DEFENSE SUPPLY CENTER COLUMBUS P. O. BOX 3990 COLUMBUS, OHIO 43216-5000										
MICRO	STANDARD MICROCIRCUIT DRAWING CHECKED BY Robert M. Heber							JOLUI	MDUS	, Onic	7 432	10-500	, , ,							
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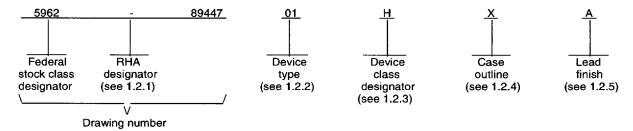
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DISTRIBUTION STATEMENT A. Approved for public release; distribution is unlimited.

5962-E097-98

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1. SCOPE

- 1.1 <u>Scope</u>. This drawing documents five product assurance classes, class D (lowest reliability), class E, (exceptions), class G (lowest high reliability), class H (high reliability), and class K, (highest reliability) and a choice of case outlines and lead finishes are available and are reflected in the Part or Identifying Number (PIN). When available, a choice of radiation hardness assurance levels are reflected in the PIN.
 - 1.2 PIN. The PIN shall be as shown in the following example:



- 1.2.1 <u>Radiation hardness assurance (RHA) designator</u>. Device classes H and K RHA marked devices shall meet the MIL-PRF-38534 specified RHA levels and shall be marked with the appropriate RHA designator. A dash (-) indicates a non-RHA device.
 - 1.2.2 <u>Device type(s)</u>. The device type(s) shall identify the circuit function as follows:

		turns ratio:				
Generic number	Circuit function	<u>Direct</u>	<u>Transformer</u>			
ARX3416, ARX3436	Dual channel, driver-receiver, receiver idle normally high	1.4:1	2:1			
NHI-1501	10	1.4:1	2:1			
FC1553622	a	√ 2:1	2:1			
BUS63135II, BUS63136II		1.4:1	2:1			
CT1487-DI	u	1.4:1	2:1			
ARX3416-002	н	1.4:1	2:1			
CT1487-DFI	•	1.4:1	2:1			
ACT4436-DI, ACT4487-DI	и	1.4:1	2:1			
	ARX3416, ARX3436 NHI-1501 FC1553622 BUS63135II, BUS63136II CT1487-DI ARX3416-002 CT1487-DFI	ARX3416, ARX3436 Dual channel, driver-receiver, receiver idle normally high NHI-1501 " FC1553622 " BUS63135II, BUS63136II " CT1487-DI " ARX3416-002 " CT1487-DFI "	Generic number ARX3416, ARX3436 Dual channel, driver-receiver, receiver idle normally high NHI-1501 FC1553622 BUS63135II, BUS63136II CT1487-DI ARX3416-002 ARX3416-002 CT1487-DFI BUS6313FI CT1487-DFI BUS6313FI ARX3416-002 BUS6313FI CT1487-DFI BUS6313FI BUS63			

1.2.3 <u>Device class designator</u>. This device class designator shall be a single letter identifying the product assurance level as follows:

Device class

Device performance documentation

Coupling transformer

D, E, G, H or K

Certification and qualification to MIL-PRF-38534

1.2.4 Case outline(s). The case outline(s) shall be as designated in MIL-STD-1835 and as follows:

Outline letter	Descriptive designator	<u>Terminals</u>	Package style
U	See figure 1	28	Dual-in-line
X	See figure 1	36	Dual-in-line
Y	See figure 1	36	Flat package
Z	See figure 1	36	Flat package

1/ Device types 01, 05, and 07 are inactive for new design. Device type 08 replaces device types 01, 05, and 07.

Device type 06, the generic number CT1892-500 is obsolete as of the date of revision B and generic number 3416-511 is obsolete as of the date of revision C.

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1.2.5 Lead finish. The lead finish shall be as specified in MIL-	PRF-38534.		
1.3 Absolute maximum ratings. 1/			
Supply voltage range: VCC (devices 01, 02, 05, 06, 07, and 08) VEE (devices 01, 03, 04, 05, 06, 07, and 08) VCC1 (all devices) Logic input voltage Receiver differential voltage Receiver common mode voltage range Driver peak output current Power dissipation (P _D) at T _C = +125°C: (devices 01, 06, and 08) (device 02) (device 03) (device 04) (devices 05 and 07) Storage temperature range Lead temperature (soldering, 10 seconds) Junction temperature (T _J): (devices 01, 03, 06, and 08) (device 02) (device 04) (devices 05 and 07) Thermal resistance, junction-to-case (θ _{JC}): (devices 01, 06, and 08) (device 02) (device 02) (device 03)	+0.3 V d0.3 V d0.3 V d0.3 V d 40 VP-F10 V d 200 mA 2 W 0.96 W 1.65 W 3 W 2/ 3.8 W 2/ +167°C +167°C +150°C +150°C 88°C/W 88°C/W 88°C/W	c to +10 V dc 2/ c +150°C c c 3/ 4/ c 3/ 5/ c 3/ 6/ c 3/	
(device 03)			
(devices 05 and 07)			
1.4 Recommended operating conditions. Supply voltage range: VCC (devices 01, 02, 05, 06, 07, and 08)	+14.25 14.25	V dc to +15.75 V dc V dc to -15.75 V dc	
V _{CC1} (all devices)	+4.5 V 0 V dc	dc to +5.5 V dc to +5 V dc	
(devices 01, 02, 05, 06, 07, and 08)	30 Vp.	P	
(devices 01, 03, 04, 06, and 08)	5 V do	to +5 V dc lc to +10 V dc	
Driver peak output current (all devices)	180 m/	4	
Serial data rate Case operating temperature range (T _C)	1.0 MH	Iz maximum to +125°C	
1/ Stresses above the absolute maximum rating may cause possible maximum levels may degrade performance and affect relia One channel transmitting at 100 percent duty cycle and the Worst case operating junction temperature when case is he Maximum junction temperature rise above case temperature 42°C. 5/ Maximum junction temperature rise above case temperature 20°C. 6/ Maximum junction temperature rise above case temperature 21°C.	ermanent damage bility. e second channel eld to +125°C. re for the hottest of re for the hottest of	e to the device. Extended of at standby. lie at 100% transmitting dur lie at 100% transmitting dur	ty cycle shall be
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2. APPLICABLE DOCUMENTS

2.1 <u>Government specification, standards, and handbook</u>. The following specification, standards, and handbook form a part of this drawing to the extent specified herein. Unless otherwise specified, the issues of these documents are those listed in the issue of the Department of Defense Index of Specifications and Standards (DoDISS) and supplement thereto, cited in the solitation.

SPECIFICATION

DEPARTMENT OF DEFENSE

MIL-PRF-38534 - Hybrid Microcircuits, General Specification for.

STANDARDS

DEPARTMENT OF DEFENSE

MIL-STD-883 - Test Methods and Procedures for Microelectronics.

MIL-STD-973 - Configuration Management.
MIL-STD-1835 - Microcircuit Case Outlines.

HANDBOOK

DEPARTMENT OF DEFENSE

MIL-HDBK-780 - Standard Microcircuit Drawings.
MIL-HDBK-1553 - Multiplex Applications Handbook.

(Unless otherwise indicated, copies of the specification, standards, and handbook are available from the Standardization Document Order Desk, 700 Robbins Avenue, Building 4D, Philadelphia, PA 19111-5094.)

2.2 <u>Order of precedence</u>. In the event of a conflict between the text of this drawing and the references cited herein, the text of this drawing takes precedence. Nothing in this document, however, supersedes applicable laws and regulations unless a specific exemption has been obtained.

3. REQUIREMENTS

- 3.1 Item requirements. The individual item performance requirements for device classes D, E, G, H, and K shall be in accordance with MIL-PRF-38534. Compliance with MIL-PRF-38534 may include the performance of all tests herein or as designated in the device manufacturer's Quality Management (QM) plan or as designated for applicable device class. Therefore, the tests and inspections herein may not be performed for applicable device class (see MIL-PRF-38534). Futhermore, the manufacturers may take exceptions or use alternate methods to the tests and inspections herein and not perform them. However, the performance requirements as defined in MIL-PRF-38534 shall be met for the applicable device class. The modification in the QM plan shall not affect the form, fit, or function as described herein.
- 3.2 <u>Design, construction, and physical dimensions</u>. The design, construction, and physical dimensions shall be as specified in MIL-PRF-38534 and herein.
 - 3.2.1 Case outline(s). The case outline(s) shall be in accordance with 1.2.4 herein and figure 1.
 - 3.2.2 Terminal connections. The terminal connections shall be as specified on figure 2.

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- 3.2.3 Timing waveforms. Timing waveforms shall be as specified on figure 3.
- 3.2.4 Typical transformer connection. The typical transformer connection shall be as specified on figure 4.
- 3.3 <u>Electrical performance characteristics</u>. Unless otherwise specified herein, the electrical performance characteristics are as specified in table I and shall apply over the full specified operating temperature range.
- 3.4 <u>Electrical test requirements</u>. The electrical test requirements shall be the subgroups specified in table II. The electrical tests for each subgroup are defined in table I.
- 3.5 <u>Marking of Device(s)</u>. Marking of device(s) shall be in accordance with MIL-PRF-38534. The device shall be marked with the PIN listed in 1.2 herein. In addition, the manufacturer's vendor similar PIN may also be marked as listed in QML-38534.
- 3.6 <u>Data</u>. In addition to the general performance requirements of MIL-PRF-38534, the manufacturer of the device described herein shall maintain the electrical test data (variables format) from the initial quality conformance inspection group A lot sample, for each device type listed herein. Also, the data should include a summary of all parameters manually tested, and for those which, if any, are guaranteed. This data shall be maintained under document revision level control by the manufacturer and be made available to the preparing activity (DSCC-VA) upon request.
- 3.7 <u>Certificate of compliance</u>. A certificate of compliance shall be required from a manufacturer in order to supply to this drawing. The certificate of compliance (original copy) submitted to DSCC-VA shall affirm that the manufacturer's product meets the performance requirements of MIL-PRF-38534 and herein.
- 3.8 <u>Certificate of conformance</u>. A certificate of conformance as required in MIL-PRF-38534 shall be provided with each lot of microcircuits delivered to this drawing.
 - 4. QUALITY ASSURANCE PROVISIONS
- 4.1 <u>Sampling and inspection</u>. Sampling and inspection procedures shall be in accordance with MIL-PRF-38534 or as modified in the device manufacturer's Quality Management (QM) plan. The modification in the QM plan shall not affect the form, fit, or function as described herein.
 - 4.2 Screening. Screening shall be in accordance with MIL-PRF-38534. The following additional criteria shall apply:
 - a. Burn-in test, method 1015 of MIL-STD-883.
 - (1) Test condition A, B, C, or D. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to either DSCC-VA or the acquiring activity upon request. Also, the test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in test method 1015 of MIL-STD-883.
 - (2) T_C as specified in accordance with table I of method 1015 of MIL-STD-883.
 - b. Interim and final electrical test parameters shall be as specified in table II herein, except interim electrical parameter tests prior to burn-in are optional at the discretion of the manufacturer.

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	Test	Symbol	Conditions 1/	Device	Group A	Lir	mits	Unit
			-55°C ≤ T _C ≤ +125°C unless otherwise specified	types	subgroups	Min	Max	
Receiver	Input level	VI	Differential input, pin 20 to pin 21 2/ pin 29 to pin 30	All	4, 5, 6		51	V _{P-P}
	Input common mode voltage	VICM	Independent of xfmr or in accordance with MIL-HDBK-1553	01,03,04, 06, 08	4, 5, 6	-5	+5	V(pk)
	range		section 5.1.2.2	02,05,07		-10	+10	
	Output low voltage	VOL	IOL = 4 mA	All	1, 2, 3		0.5	v
			I _{OL} = 16 mA	04			0.5	
	Output high voltage	Vон	I _{OH} = -0.4 mA	All	1, 2, 3	2.5		v
Transmitter	Input low voltage	VIL		All	1, 2, 3		0.7	v
	Input high voltage	VIH		All	1, 2, 3	2		٧
	Input low current	IIL	V _{IL} = 0.4 V	01,02,03, 06, 08	1, 2, 3	-0.4		mA
				04,05,07		-1.0		
	Input high current	ин	V _{IH} = 2.7 V	All	1, 2, 3		0.04	mA
	Output voltage	vo	Across 35Ω load	All	1, 2, 3	6	9	Vp-P
	Output noise voltage	VON	Across 35Ω load	All	4, 5, 6		10	mVP-

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	Test	Symbol	Conditions 1/	Device	Group A	Lim	nits	Unit
			-55°C ≤ T _C ≤ +125°C unless otherwise specified	types	subgroups	Min	Max	
Receiver strobe	Input low voltage	VSIL		All	1, 2, 3		0.7	v
	Input high voltage	VSIH		All	1, 2, 3	2		٧
	Input low current	ISIL	V _{SIL} = 0.4 V	01,06,08	1, 2, 3	-0.4		mA
				02,04	<u> </u>	-0.72		
				03		-0.7		
				05,07		-1.0		
•	Input high current	ISIH	V _{SIH} = 2.7 V	All	1, 2, 3		0.04	mA
Transmitter inhibit	Input low voltage	VIIL		All	1, 2, 3		0.7	v
	Input high voltage	VIIH		All	1, 2, 3	2		v
	Input low current	IIIL	V _{SIL} = 0.4 V	01,02,03, 06,08	1, 2, 3	-0.4		mA
				04	1	-0.72		
				05,07		-1.0		
	Input high current	чн	V _{SIH} = 2.7 V	01,02,03, 04,06,08	1, 2, 3		0.04	mA
	,			05,07			0.08	

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	Test	Symbol	Conditions	<u>1</u> /	Device	Group A	Lir	nits	Unit
			-55°C ≤ T _C ≤ unless otherwise	+125°C specified	types	subgroups	Min	Мах	
Power supply	Total current	I _{CC} -SB	(standby mode)		01,08 02 05,06,07	1, 2, 3		1 25 22	mA
		I _{EE} -SB			01,03,08 04 05,06,07	1, 2, 3		16.5 30 35	
		I _{CC1} -SB			01,08 02 03 04,05,06,	1, 2, 3		30 25 35 45	
		I _{CC} -25	(25% duty cycle into 35Ω load		01,08 02 05,06,07	4, 5, 6		55 69 80	<u> </u>
		I _{EE} -25			01,08 03 04 05,06,07	4, 5, 6		21 15 80 35	
		I _{CC1} -25			01,08 02 03,04,05, 06,07	4, 5, 6		30 25 45	
	I _{CC} -50	I _{CC} -50	(50% duty cycle into 35Ω load)		01,08 02 05,06,07	4, 5, 6		110 118 130	
		IEE-50	<u> </u>		01,08 03,04 05,06,07	4, 5, 6		25 130 35	
		ICC1-50			01,08 02 03,04,05, 06,07	4, 5, 6		30 25 45	
Con fortact		I _{CC} -100	(100% duty cycle into 35Ω load)	•	01,08 02 05,06,07	1, 2, 3		220 209 240	
		I _{EE} -100			01,08 03,04 05,06,07	1, 2, 3		30 255 35	
See tootno	tes at end of table.								
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	Test	Symbol	Conditions 1/	Device	Group A	Lim	its	Unit
			-55°C ≤ T _C ≤ +125° unless otherwise specif	C types ied	subgroups	Min	Мах	
Power supply	Total current	ICC1-100	(100% duty cycle into 35Ω load)	01,08 02 03 04,05,06	1, 2, 3		30 25 55 45	mA
Receiver	Input resistance	R _{IN}	1 MHz sine wave	01,02,08 03,04 05,06,07		10 7 9		kΩ
	Input capacitance	CIN	1 MHz sine wave 2/ T _C = +25°C	All	4		5	pF
	Threshold voltage	VTH	<u>3</u> /	01,06,08	1, 2, 3	0.6	1.05	V _{P-P}
				02		0.6	1.10	
				03		0.6	1.15	<u> </u>
				04	<u> </u>	0.56	1.0	ļ
				05,07		0.8	1.1	
Transmitter	Output resistance (transmitter off)	ROUT	1 MHz sine wave 2/	01,02,03 04,06,08		10		kΩ
	J 511)			05,07		8		
	Output capacitance (transmitter off)	COUT	1 MHz sine wave 2/ T _C = +25°C	All	4		5	pF
	Output offset voltage	vos	2/4/	All	4, 5, 6		±90	mV(pk)
	Peak amplitude variation	Av	5/	All	4, 5, 6		±15	%
	Zero cross stability	ts1	Across 35Ω 2/ (See figure 3)	06	9,10,11	1975	2025	ns
		tS2				475	525	
		tS3				975	1025	
		ts4				1475	1525	
See footnote	es at end of table.			1		· L		-
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	Test	Symbol	Conditions 1/	Device	Group A subgroups	Lir	mits	Unit
			-55°C ≤ T _C ≤ +125°C unless otherwise specified	types		Min	Max	
Receiver	Delay time, input to output	tDR	Delay time from dif- 2/ ferential input zero crossing to DATA or	01,02,03, 04,06,08	9,10,11		400	ns
			DATA (See figure 3)	05,07			350	1
	Strobe delay	tDS	Delay time from strobe rising or	01,03,05, 06,07,08	9,10,11		250	
			falling edge to DATA or DATA (See figure 3) 2/	02,04			200	
Transmitter	Rise time	tR	Output load = 35Ω (See figure 3)	01,02,03, 04,05,07, 08	9,10,11	100	300	ns
				06		100	200	
	Fall time	tF		01,02,03, 04,05,07, <u>08</u>	9,10,11	100	300	
				06		100	200	
	Delay time inhibiting	^t DT	(See figure 3) 2/	01,03,06, <u>08</u>	9,10,11		350	
				02,04			250	
				05,07			200	
	Inhibit delay inhibiting	tDI-H	(See figure 3) 2/	01,02,06, <u>08</u>	9,10,11		200	
				03,04			450	
				05,07			225	
	Inhibit delay active	^t DI-L	(See figure 3) 2/	01,02,06, 08	9,10,11		200	
				03,04			450	
				05,07			150	

^{1/} V_{CC} = 15 V, V_{EE} = -15 V, V_{CC1} = +5 V. All specifications and limits are for a single channel with no connections made to the other channel.

2/ This parameter is tested initially and after any process or design change which might affect this parameter.

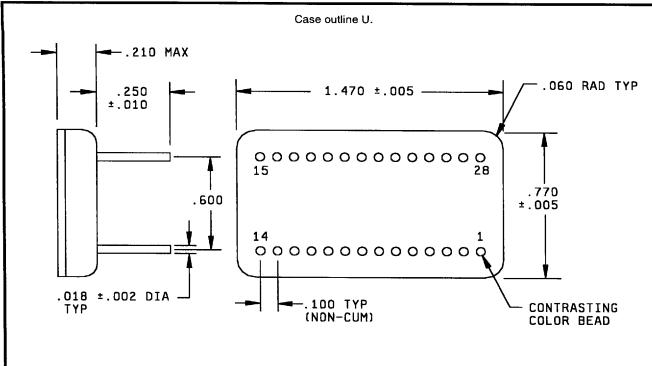
5/ Measured across 35Ω load, variation of average peak amplitude.

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Threshold is measured in direct coupled mode including the transformer. Threshold is the maximum level on the BUS at which there are no pulses on either receiver output. Divide by 1.4 to obtain threshold in transformer coupled mode.
 Measured across 35Ω load, 2.5 μs after parity bit mid-bit zero crossing of a 660 μs message.



Inches	mm
.002	0.05
.005	0.13
.010	0.25
.018	0.46
.060	1.52
.100	2.54
.210	5.33
.250	6.35
.600	15.24
.770	19.56
1.470	37.34

NOTES:

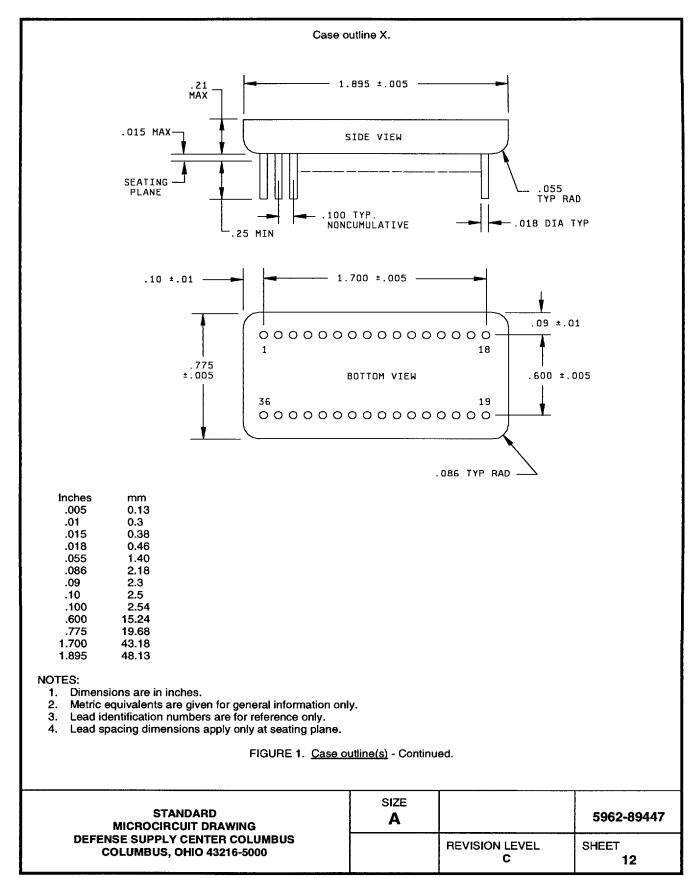
- 1. Dimensions are in inches.
- 2. Metric equivalents are given for general information only.
- Lead indentification numbers are for reference only.
 Lead spacing dimensions apply only at seating plane.

FIGURE 1. Case outline(s).

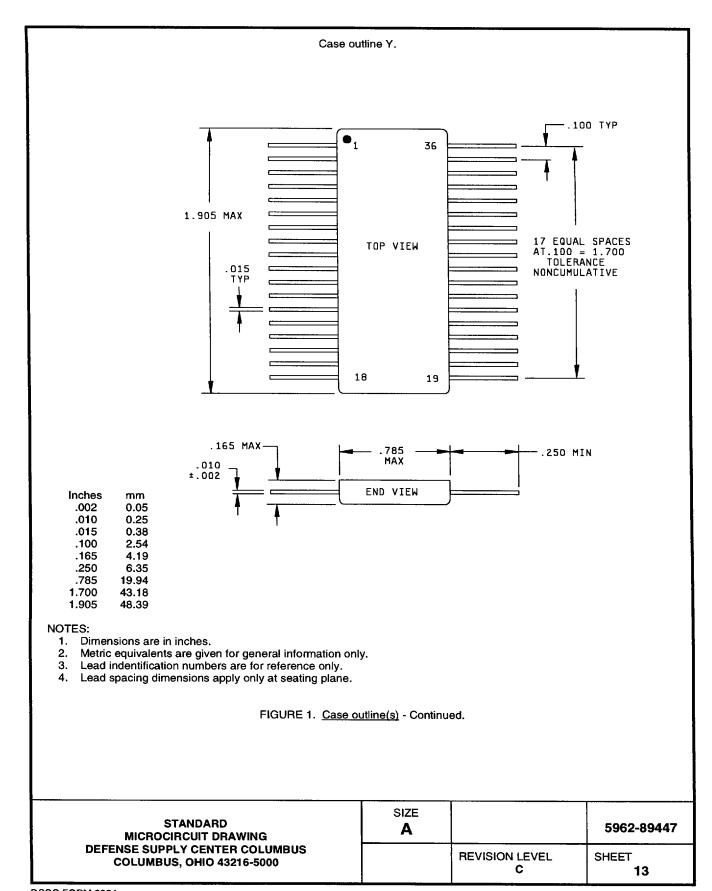
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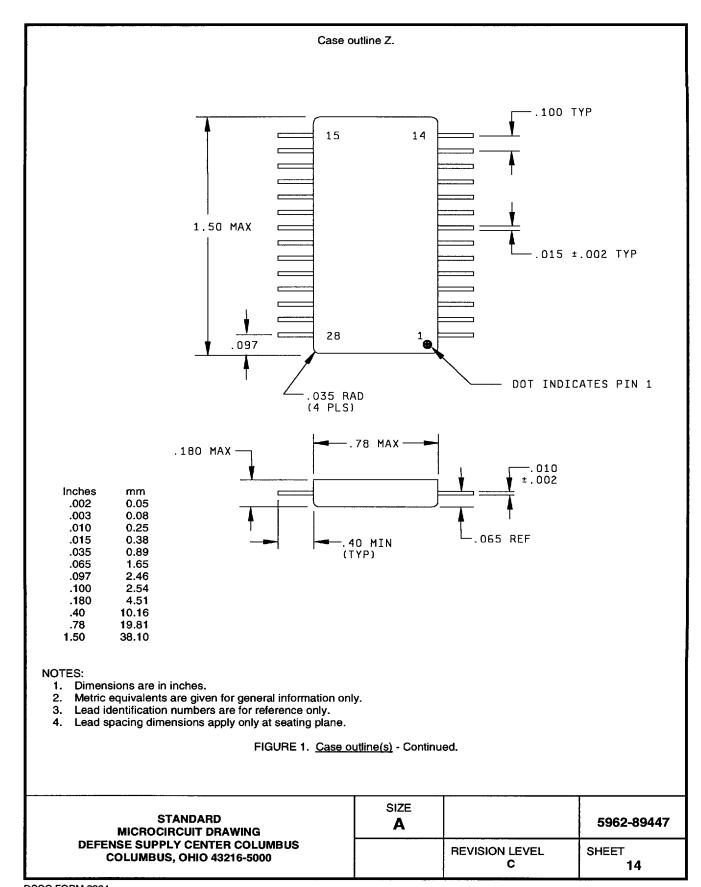
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Case outlines X and Y.

1 TX data out One 2 TX data out One 3 GND or NC One 4 NC One 5 RX data out One 6 Strobe One 7 GND One 8 RX data out One 9 GND or Case One 10 TX data out Two 11 TX data out Two 12 GND or NC Two 13 NC Two 14 RX data out Two 15 Strobe Two 16 GND Two 17 RX data out Two 18 NC Two 19 VCC, or NC Two 20 RX data in Two 21 RX data in Two 23 VEE or NC Two 24 VCC1 Two 25 Inhibit Two </th <th>Pin</th> <th>Function</th> <th>Channel</th>	Pin	Function	Channel
1 11 2 11 11	2 3 4 5 6 7 8 9 10 11 12 13 14 15 16 17 18 19 20 21 22 24 25 26 27 28 29 30 31 32 33 34 34	TX data out GND or NC NC RX data out Strobe GND RX data out GND or Case TX data out GND or NC NC RX data out GND or NC NC RX data out Strobe GND RX data out Strobe GND RX data in RX data in RX data in RX data in TX data in RX data in CND or NC VCC, or NC RX data in RX data in TX data in RX data in GND or NC VCC1 Inhibit	One One One One One One One One One Two

NOTE:

GND pins should all be connected externally. For case outlines X and Y only, pins 19 and 28 are V_{CC} for device types 01, 02, 05, 06, and 07 and no connects (NC's) for device types 03 and 04. Also, for case outlines X and Y only, pins 23 and 32 are V_{EE} for device types 01, 03, 04, 05, 06, and 07 and no connects (NC's) for device type 02.

FIGURE 2. Terminal connections.

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Case outlines U and Z. (Device types 01 and 08).

Pin	Function	Channel
1 2 3 4 5 6 7 8 9 10 11 12 13 14 15 16 17 18 19 20 21 22 23 24 25 26 27	TX data out/RX data in TX data out/RX data in GND RX strobe RX data out RX data in TX data out Case TX data out/RX data in TX data out/RX data in TX data out/RX data in GND RX strobe RX data out RX data out No connect GND VEE VCC1 TX inhibit TX data in	One One One One One One Two
28	VCC	One

NOTE:

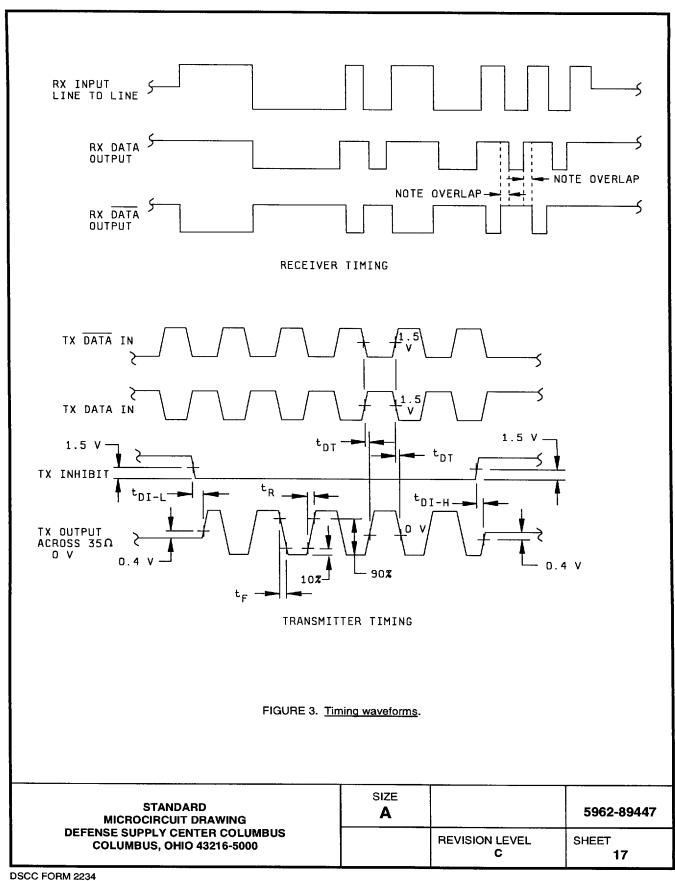
1. GND pins should all be connected externally.

FIGURE 2. Terminal connections - Continued.

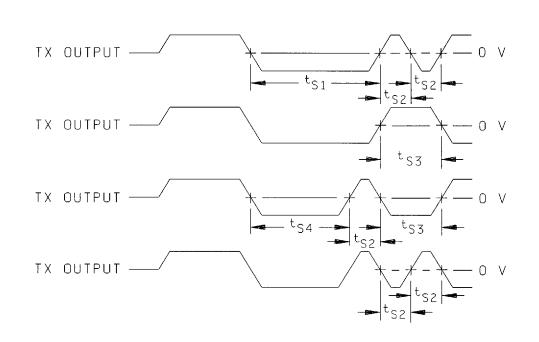
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DEFENSE SUPPLY CENTER COLUMBUS		REVISION LEVEL	SHEET
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9004708 0037240 095



TRANSMISSION ZERO CROSS STABILITY

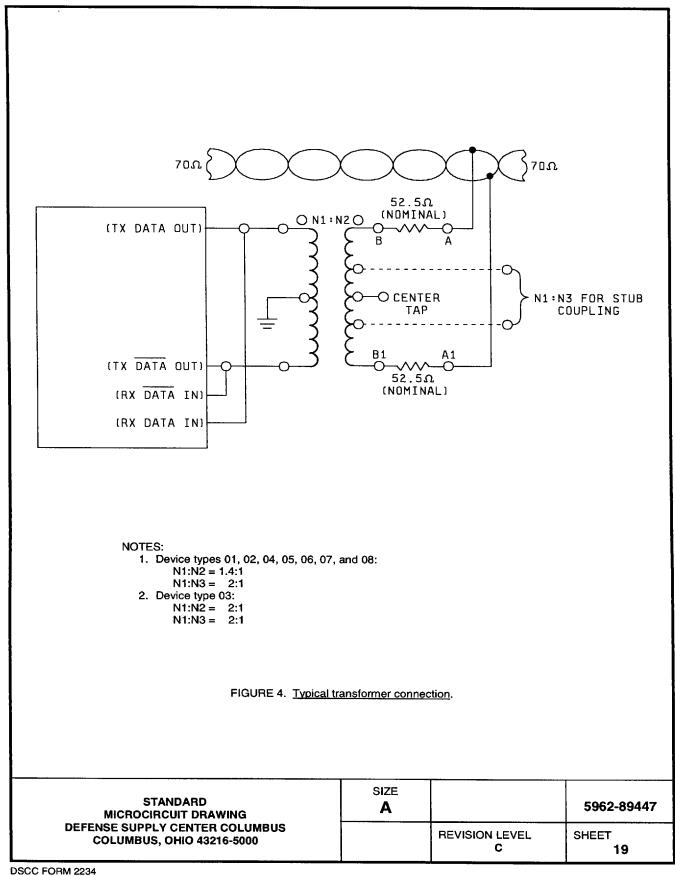
NOTE: Abbreviated waveform. Above relationships apply during entire transmission.

FIGURE 3. Timing waveforms - Continued.

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TABLE II. Electrical test requirements.

MIL-PRF-38534 test requirements	Subgroups (in accordance with MIL-PRF-38534, group A test table)
Interim electrical parameters	
Final electrical parameters	1*,2,3,4,5,6,9,10,11
Group A test requirements	1,2,3,4,5,6,9,10,11
Group C end-point electrical parameters	1,2,3
MIL-STD-883, group E end-point electrical parameters for RHA devices	Subgroups** (in accordance with method 5005, group A test table)

- * PDA applies to subgroup 1.
- ** When applicable to this standard microcircuit drawing, the subgroups shall be defined.
- 4.3 <u>Conformance and periodic inspections</u>. Conformance inspection (CI) and periodic inspection (PI) shall be in accordance with MIL-PRF-38534 and as specified herein.
- 4.3.1 Group A inspection (CI). Group A inspection shall be in accordance with MIL-PRF-38534 and as follows:
 - a. Tests shall be as specified in table II herein.
 - b. Subgroups 7 and 8 shall be omitted.
- 4.3.2 Group B inspection (PI). Group B inspection shall be in accordance with MIL-PRF-38534.
- 4.3.3 Group C inspection (PI). Group C inspection shall be in accordance with MIL-PRF-38534 and as follows:
 - a. End-point electrical parameters shall be as specified in table II herein.
 - b. Steady-state life test, method 1005 of MIL-STD-883.
 - (1) Test condition A, B, C, or D. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to either DSCC-VA or the acquiring activity upon request. Also, the test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in test method 1005 of MIL-STD-883.
 - (2) T_C as specified in accordance with table I of method 1005 of MIL-STD-883.
 - (3) Test duration: 1,000 hours, except as permitted by method 1005 of MIL-STD-883.

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- 4.3.4 Group D inspection (PI). Group D inspection shall be in accordance with MIL-PRF-38534.
- 4.3.5 <u>Group E inspection</u>. Group E inspection is required only for parts intended to be marked as radiation hardness assured (see 3.5 herein). RHA levels for device classes H and K shall be M, D, R, and H. RHA quality conformance inspection sample tests shall be performed at the RHA level specified in the acquisition document.
 - a. RHA tests for device classes H and K for levels M, D, R, and H shall be performed through each level to determine at what levels the devices meet the RHA requirements. These RHA tests shall be performed for initial qualification and after design or process changes which may affect the RHA performance of the device.
 - b. End-point electrical parameters shall be as specified in table II herein.
 - c. Prior to total dose irradiation, each selected sample shall be assembled in its qualified package. It shall pass the specified group A electrical parameters in table I for subgroups specified in table II herein.
 - d. For device classes H and K, the devices shall be subjected to radiation hardness assured tests as specified in MIL-PRF-38534 for RHA level being tested, and meet the postirradiation end-point electrical parameter limits as defined in table I at T_A = +25°C ±5 percent, after exposure.
 - Prior to and during total dose irradiation testing, the devices shall be biased to establish a worst case condition as specified in the radiation exposure circuit.
 - f. For device classes H and K, subgroups 1 and 2 in table V, method 5005 of MIL-STD-883 shall be tested as appropriate for device construction.
 - g. When specified in the purchase order or contract, a copy of the RHA delta limits shall be supplied.

5. PACKAGING

5.1 Packaging requirements. The requirements for packaging shall be in accordance with MIL-PRF-38534.

6. NOTES

- 6.1 <u>Intended use</u>. Microcircuits conforming to this drawing are intended for use for Government microcircuit applications (original equipment), design applications, and logistics purposes.
- 6.2 <u>Replaceability</u>. Microcircuits covered by this drawing will replace the same generic device covered by a contractor-prepared specification or drawing.
- 6.3 <u>Configuration control of SMD's</u>. All proposed changes to existing SMD's will be coordinated with the users of record for the individual documents. This coordination will be accomplished in accordance with MIL-STD-973 using DD Form 1692, Engineering Change Proposal.
- 6.4 <u>Record of users</u>. Military and industrial users shall inform Defense Supply Center Columbus when a system application requires configuration control and the applicable SMD. DSCC will maintain a record of users and this list will be used for coordination and distribution of changes to the drawings. Users of drawings covering microelectronic devices (FSC 5962) should contact DSCC-VA, telephone (614) 692-7603.
- 6.5 Comments. Comments on this drawing should be directed to DSCC-VA, P. O. Box 3990, Columbus, Ohio 43216-5000, or telephone (614) 692-0676.
- 6.6 <u>Sources of supply</u>. Sources of supply are listed in QML-38534. The vendors listed in QML-38534 have submitted a certificate of compliance (see 3.7 herein) to DSCC-VA and have agreed to this drawing.

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MICROCIRCUIT DRAWING
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A

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STANDARD MICROCIRCUIT DRAWING SOURCE APPROVAL BULLETIN

DATE: 98-06-05

Approved sources of supply for SMD 5962-89447 are listed below for immediate acquisition only and shall be added to QML-38534 during the next revision. QML-38534 will be revised to include the addition or deletion of sources. The vendors listed below have agreed to this drawing and a certificate of compliance has been submitted to and accepted by DSCC-VA. This bulletin is superseded by the next dated revision of QML-38534.

Standard	Vendor	Vendor
microcircuit drawing	CAGE	similar
PIN <u>1</u> /	number	PIN <u>2</u> /
5962-8944701HUX	3/	ARX3436-502
5962-8944701HXX	3/	ARX3416-001-3
5962-8944701HYX	3/	ARX3416FP-001-3
5962-8944701HZX	3/	ARX3436FP-502
5962-8944702HXA	57363	NHI-1501/883
5962-8944702HXC	57363	NHI-1501/883
5962-8944702HYA	57363	NHI-1501FP/883
5962-8944702HYC	57363	NHI-1501FP/883
5962-8944703HXA	U4388	FC1553622
5962-8944703HXC	U4388	FC1553622
5962-8944703HYA	U4388	FC1553622FP
5962-8944703HYC	U4388	FC1553622FP
5962-8944704HXC	19645	BUS63135II
5962-8944704HYC	19645	BUS63136II
5962-8944705HXX	<u>3</u> /	CT1487-DI
5962-8944706HXA	88379	ARX3416-002-2
5962-8944706HXC	88379	ARX3416-002-2
5962-8944707HYX	<u>3</u> /	CT1487-DFI

- 1/ The lead finish shown for each PIN, representing a hermetic package, is the most readily available from the manufacturer listed for that part. If the desired lead finish is not listed contact the Vendor to determine availability.
- <u>Caution</u>. Do not use this number for item acquisition. Items acquired to this number may not satisfy the performance requirements of this drawing.
- 3/ Not available from a QML-38534 source. Device type 08 replaces device types 01, 05, and 07.

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STANDARD MICROCIRCUIT DRAWING SOURCE APPROVAL BULLETIN - Continued.

DATE: 98-06-05

Standard	Vendor	Vendor
microcircuit drawing	CAGE	similar
PIN <u>1</u> /	number	PIN <i>2/</i>
5962-8944708HUA	88379	ACT4436-DI
5962-8944708HUC	88379	ACT4436-DI
5962-8944708HXA	88379	ACT4487-DI
5962-8944708HXC	88379	ACT4487-DI
5962-8944708HYA	88379	ACT4487-DFI
5962-8944708HYC	88379	ACT4487-DFI
5962-8944708HZA	88379	ACT4436-DFI
5962-8944708HZC	88379	ACT4436-DFI

- The lead finish shown for each PIN, representing a hermetic package, is the most readily available from the manufacturer listed for that part. If the desired lead finish is not listed contact the Vendor to determine
- availability.

 <u>Caution</u>. Do not use this number for item acquisition. Items acquired to this number may not satisfy the <u>2</u>/ performance requirements of this drawing.

 Not available from a QML-38534 source. Device type 08 replaces device types 01, 05, and 07.

Vendor CAGE number_	Vendor name <u>and address</u>
U4388	C-MAC Microcircuits Limited South Denes Great Yarmouth Norfolk NR30 3PX England
19645	ILC Data Device Corporation 105 Wilbur Place Bohemia, NY 11716-2482
57363	National Hybrid, Incorporated 2200 Smithtown Avenue Ronkonkoma, NY 11779-7359
88379	Aeroflex Circuit Technology Corporation 35 South Service Road Plainview, NY 11803-4193

The information contained herein is disseminated for convenience only and the Government assumes no liability whatsoever for any inaccuracies in this information bulletin.

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